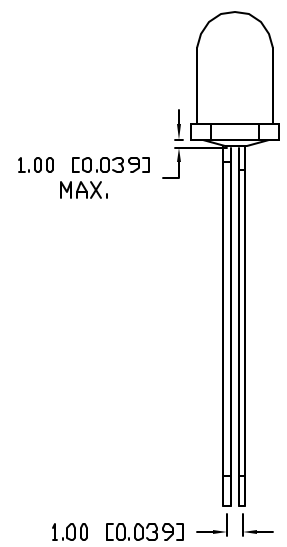
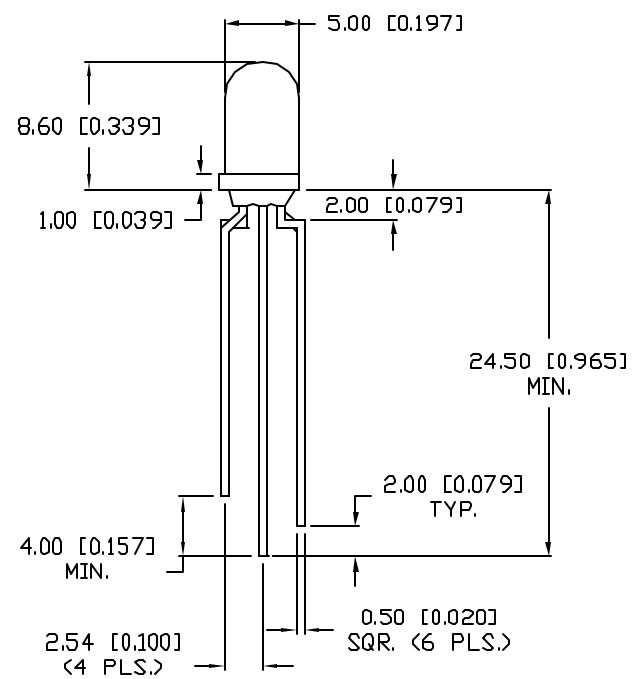


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PART NUMBER
SSL-LX5099IHCLELC
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PRELIMINARY IN P/N DIR



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	RED	RED	IR	IR	UNITS	TEST COND
PEAK WAVELENGTH	635	700	860	940	nm	
FORWARD VOLTAGE (TYP.)	2.0	2.2	1.35	1.2	V_f	
FORWARD VOLTAGE (MAX.)	2.5	2.5	1.6	1.6	V_f	
REVERSE VOLTAGE (TYP.)	5.0	5.0	5.0	5.0	V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY (TYP.)	35	2.5			mcd	$I_f=20\text{mA}$
RADIANT INTENSITY			15	10	mW/SR	$I_f=20\text{mA}$
SPECTRAL BANDWIDTH			50	50	nm	$I_f=20\text{mA}$
VIEWING ANGLE	30	30	30	30	2x theta	
LED POSITION:	1	2	3	4		
EPOXY LENS FINISH:	WATER CLEAR					

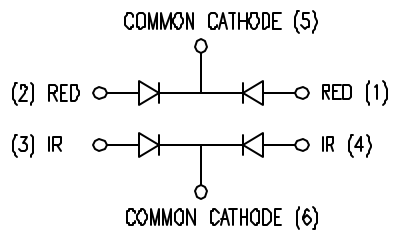
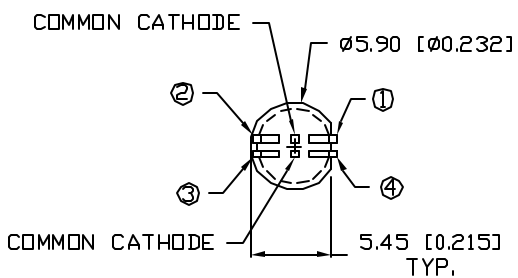
LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*	(1/2/3/4)	180/130/1000/1200	mA
STEADY CURRENT	(1/2/3/4)	30/25/50/50	mA
POWER DISSIPATION	(1/2/3/4)	75/62/80/80	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING, STORAGE TEMP.		-40 TO +85	°C
SOLDERING TEMP.		+260	°C
2.0mm FROM BODY			3 SEC. MAX

* $t < 10\mu\text{s}$



BOTTOM VIEW POLARITY



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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=^{+DECIMAL PRECISION}-0.00 ^{MAX.=+0.00}-DECIMAL PRECISION

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T-5mm (T-1 3/4) LED, 6 LEADED, MULTI-COLORED,
635nm RED, 700nm RED, 940nm IR, 860nm IR,
WATER CLEAR LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC
CHECKED BY:
APPROVED BY:
DATE: 4.19.07
PAGE: 1 OF 1
SCALE: N/A